

## 20V P-Channel Enhancement Mode Power MOSFET

# **Description**

WMQ55P02T1 uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

## **Features**

- $V_{DS}$ = -20V,  $I_{D}$  = -55A  $R_{DS(on)}$  < 8.2m $\Omega$  @  $V_{GS}$  = -4.5V  $R_{DS(on)}$  < 10m $\Omega$  @  $V_{GS}$  = -2.5V
- Green Device Available
- Low Gate Charge
- Advanced High Cell Density Trench Technology
- 100% EAS Guaranteed

# **Applications**

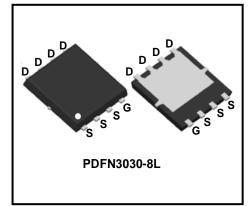
- High Current Load Applications
- Load Switching
- Hard Switched And High Frequency Circuits
- Uninterruptible Power Supply

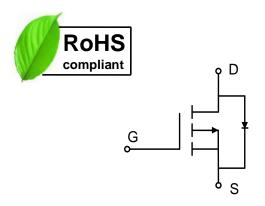
# **Absolute Maximum Ratings**

Parameter		Symbol	Value	Unit	
Drain-Source Voltage		V <sub>DS</sub>	-20	V	
Gate-Source Voltage		V <sub>GS</sub>	±10	V	
Continuous Ducin Coursett	T <sub>C</sub> =25°C		-55	•	
Continuous Drain Current <sup>1</sup>	T <sub>C</sub> =100°C	- I <sub>D</sub>	-35	А	
Pulsed Drain Current <sup>2</sup>		I <sub>DM</sub>	-120	А	
Single Pulse Avalanche Energy <sup>3</sup>		EAS	20	mJ	
Avalanche Current		las	-20	А	
Total Power Dissipation <sup>4</sup>	Tc=25°C	P <sub>D</sub>	39	W	
Operating Junction and Storage Temperature Range		TJ, TSTG	-55 to 150	°C	

## **Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>1</sup>	R <sub>0JA</sub>	38	°C/W
Thermal Resistance from Junction-to-Case <sup>1</sup>	R <sub>eJC</sub>	3.2	°C/W





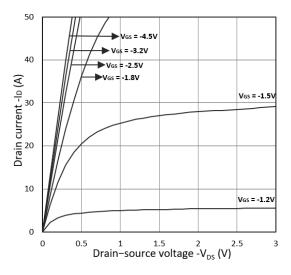


## Electrical Characteristics T<sub>c</sub> = 25°C, unless otherwise noted

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static Characteristics	J			ı	ı	I
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>G</sub> S = 0V, I <sub>D</sub> = -250µA	-20	-	-	V
Gate-body Leakage current	I <sub>GSS</sub>	$V_{DS} = 0V, V_{GS} = \pm 10V$	-	-	±100	nA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V	-	-	-1	μΑ
Gate-Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA	-0.4	-	-1.0	V
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -15A	-	6.8	8.2	mΩ
Drain-Source on-Resistance <sup>2</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -10A	-	8.5	10	
		V <sub>GS</sub> = -1.8V, I <sub>D</sub> = -8.0A	-	11.2	15	
Dynamic Characteristics	1		ı	l	l	ı
Input Capacitance	C <sub>iss</sub>		-	4550	-	pF
Output Capacitance	Coss	V <sub>DS</sub> = -10V, V <sub>GS</sub> =0V, f =1MHz	-	542	-	
Reverse Transfer Capacitance	Crss		-	505	-	
Switching Characteristics			1			I.
Total Gate Charge	Qg		-	43	-	nC
Gate-Source Charge	Q <sub>gs</sub>	$V_{GS} = -4.5V$ , $V_{DS} = -10V$ , $I_{D} = -20A$	-	7	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	9.2	-	
Turn-on Delay Time	t <sub>d(on)</sub>		-	13.5	-	
Rise Time	t <sub>r</sub>	$V_{GS} = -4.5V, V_{DD} = -10V,$	-	18.8	-	nS
Turn-off Delay Time	t <sub>d(off)</sub>	$R_G = 3\Omega$ , $I_D = -12A$ , $R_L = 1\Omega$ ,	-	92	-	. 113
Fall Time	<b>t</b> f		-	161	-	
Drain-Source Body Diode Characte	eristics					
Diode Forward Voltage <sup>2</sup>	V <sub>SD</sub>	I <sub>S</sub> = -1A, V <sub>GS</sub> = 0V	-	-	-1.2	V
Continuous Source Current <sup>1,5</sup>	Is	V <sub>G</sub> =V <sub>D</sub> = 0V , Force Current	-	-	-55	Α
Body Diode Reverse Recovery Time	t <sub>rr</sub>		-	24	-	nS
Body Diode Reverse Recovery Charge	Qrr	I <sub>F</sub> = -12A, dl/dt = 100A/μs	-	26	-	nC

#### Note:

- 1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\,\leqslant\,\,300\text{us}$  , duty cycle  $\,\leqslant\!2\%$
- 3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ = -20V,  $V_{GS}$ = -10V, L=0.1mH,  $I_{AS}$ = -20A
- 4.The power dissipation is limited by 150°C junction temperature
- 5. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



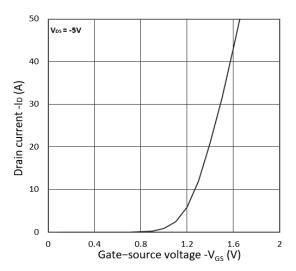
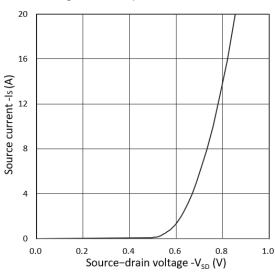


Figure 1. Output Characteristics

Figure 2. Transfer Characteristics



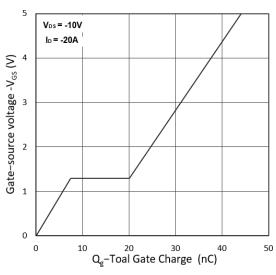
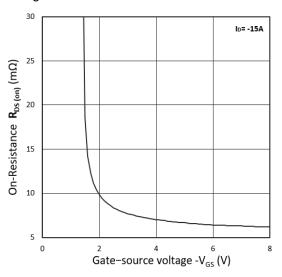


Figure 3. Forward Characteristics of Reverse

Figure 4. Gate Charge Characteristics



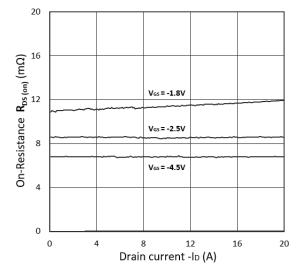


Figure 5. R<sub>DS(on)</sub> vs. V<sub>GS</sub>

Figure 6.  $R_{DS(on)}$  vs.  $I_D$ 



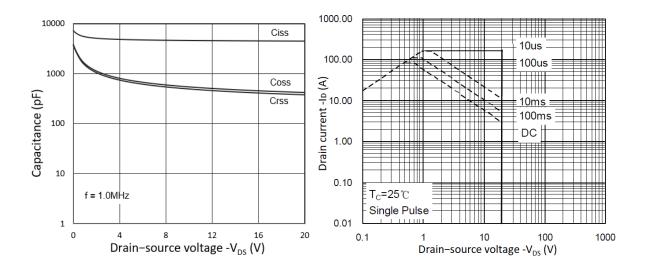


Figure 7. Capacitance Characteristics

Figure 8. Safe Operating Area

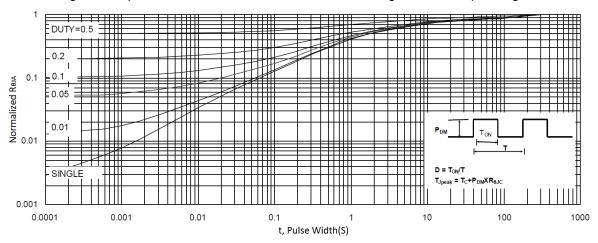


Figure 9. Normalized Maximum Transient Thermal Impedance

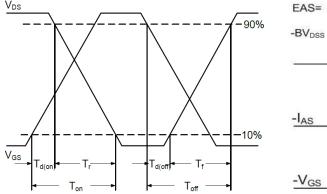


Figure 10. Switching Time Waveform

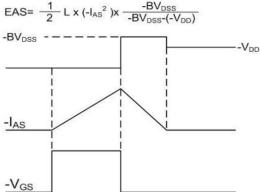


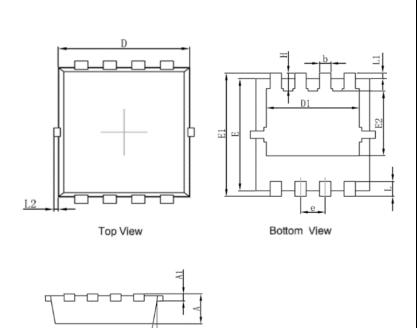
Figure 11. Unclamped Inductive Switching

Waveform

Side View



## **Mechanical Dimensions for PDFN3030-8L**



## **COMMON DIMENSIONS**

SYMBOL	MM			
	MIN	MAX		
А	0.70	0.90		
A1	0.10	0.25		
D	2.90	3.25		
D1	2.25	2.69		
E	2.90	3.20		
E1	3.00	3.60		
E2	1.54	2.20		
b	0.20	0.40		
e	0.60	0.70		
L	0.15	0.50		
L1	0.13BSC			
L2	0.00	0.20		
Н	0.15	0.65		
θ	0°	14°		



## **Ordering Information**

Part	Package	Marking	Packing method
WMQ55P02T1	PDFN3030-8L	Q55P02	Tape and Reel

## **Marking Information**



Q55P02= Device code WWXXXXX= Date code

## **Disclaimer**

WAYON reserves the right to make changes without further notice to any Products herein to improve reliability, function, or design. The Products are not designed for use in hostile environments, including, without limitation, aircraft, nuclear power generation, medical appliances, and devices or systems in which malfunction of any Product can reasonably be expected to result in a personal injury. The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics. WAYON does not assume any liability for infringement of patents, copyrights, or other intellectual property rights of third parties by or arising from the use of Products or technical information described in this document.